



# Best Paper Award

7th World Congress on Mechanical, Chemical, and Material Engineering (MCM'21)

August 02, 2021 - August 04, 2021 | ~~Prague, Czech Republic~~ - Virtual Congress |

**Presented to**

**Pei-Ing Lee**

**for the paper entitled:**

“Atomic Migration of Cu in Ti/Ni/Cu/Ag Backside Metallization on Si Substrate”

A handwritten signature in black ink that reads 'Takshasheel Pawar'.

**Takshasheel Pawar**  
**On Behalf of the Conference Chair**



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